

# φ0.075 Ultra Micro-Hole Drilling Performance

## φ0.075 ドリル 加工事例

用途: 半導体パッケージ、各種デバイス用基板 等 FBGA、BGA、Device substrate etc...

### Drilling Condition 加工条件

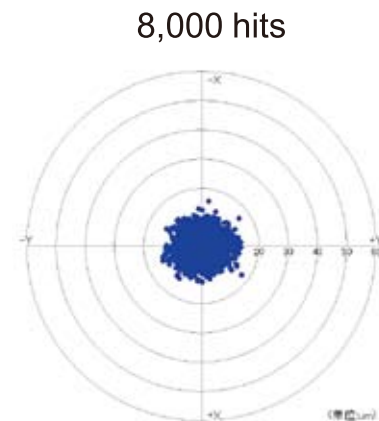
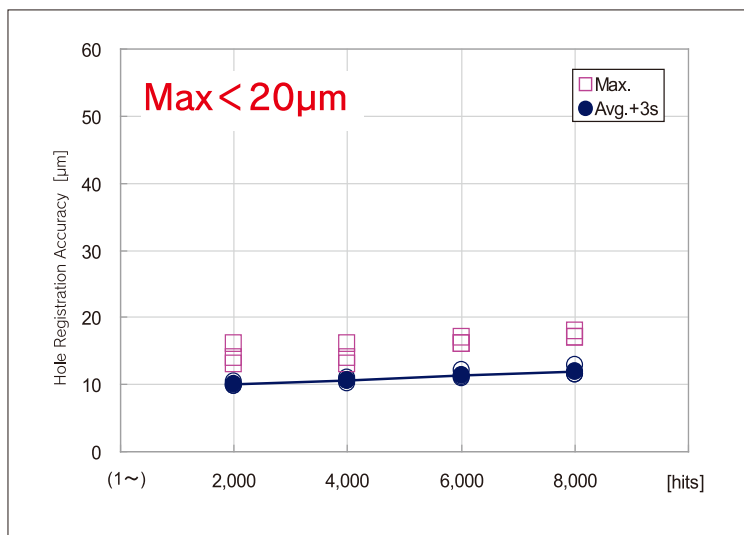
Work Material : MCL-E-679FG(R) t0.1(Double Sided) x 4 stack height 4/4μmCopper

S : 350,000 min<sup>-1</sup> F : 1.75 m/min f : 5 μm/rev

Set Life : 8,000 hits

High Quality & High Efficiency Drilling  
高品質 & 高効率加工を実現

### Hole Registration Accuracy 穴位置精度



### Hole Wall Quality at 8,000th hit 内壁粗さ

